

Description

LDPE LD 0304 is a low density polyethylene made by a high pressure autoclave process without antioxidant.

Application examples: coating of paper, paperboard, aluminium.

Characteristics

Property	Method	Unit	Typical value
Density	ISO 1183	g/cm ³	0.924
Melt Flow Rate (190°C/2.16 kg)	ISO 1133	g/10 min	4
Melting temperature	ISO 11357	°C	111
Vicat temperature	ISO 306	°C	95

Values indicated are typical for this product. Density and MFR are properties routinely measured during "the standard quality control procedure". The other figures are generated by tests not included in the "standard quality control procedure", and are given for information only. Data are not intended for specification purposes.

Processing

Temperature profile for extrusion coating: 200-320 °C

Die melt temperature: 260-320°C

Mechanical properties

Property	Method	Unit	Typical value (*)
Tensile Strength at Yield	ISO 527-2	MPa	11
Tensile Strength at Break	ISO 527-2	MPa	13
Elongation at Break	ISO 527-2	%	550
Modulus of Elasticity	ISO 527-2	MPa	250

(*) Figures stated hereabove are measured on a moulded plate.

Handling and storage

Please refer to the safety data sheet (SDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the SDS of our product. SDS may be obtained from the website:

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